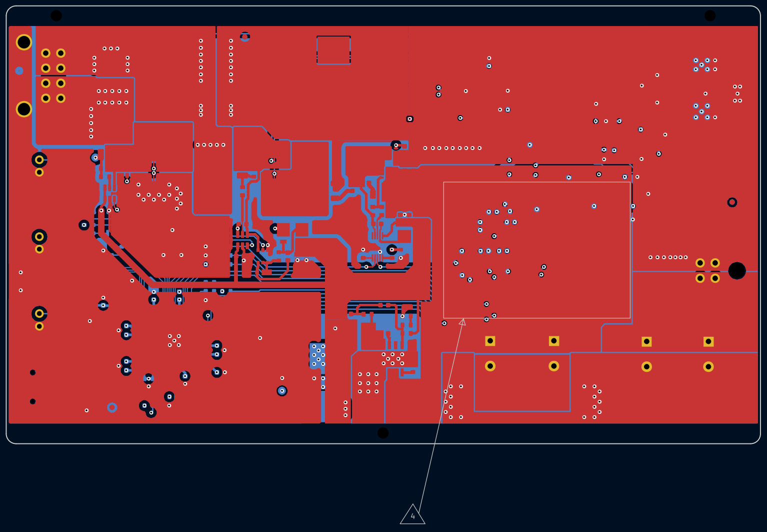

BOARD CHARACTERISTICS

Copper Layer Count:	6	Board Thickness:	60 mils
Board overall dimensions:	5905 mils x 3150 mils		
Min track/spacing:	7.80 mils / 7.80 mils	Min hole diameter:	12 mils
Copper Finish:	ENIG	Impedance Control:	No
Castellated pads:	No	Plated Board Edge:	No
Edge card connectors:	No		

FAB NOTES:

1. FABRICATE PER IPC–A–6012 CLASS 2
2. ALL DIMENSIONS SHALL BE TAKEN FROM THE ACCOMPANYING DATABASE
3. REMOVAL OF NON–FUNCTIONAL PADS IS ACCEPTABLE
4. PRINT PER GERBERS
5. FABRICATION SHALL BE CAPABLE OF WITHSTANDING ROHS LEVEL ASSEMBLY
6. PLATE ALL EXPOSED CONDUCTIVE SURFACES WITH ENIG PER IPC–4552B
7. SOLDER MASK OVER BARE COPPER IAW IPC–SM–840. BOTH SIDES USING LPI, BLACK. TOOLING HOLES TO BE FREE AND CLEAR OF SOLDER MASK AND SOLDER MASK NODULES
8. SOLDER MASK CLEARANCE 3 MIL MIN WEB
9. APPLY SILKSCREEN USING WHITE,NON–CONDUCTIVE EPOXY INK
10. COPPER PLATE TFOR THRU–HOLES SHALL HAVE 1 MIL MIN WALL THICKNESS
11. DESIGN HAS VIA–IN–PAD:
    ALL 12MIL VIAS TO BE FILLED AND CAPPED PER IPC–4761 TYPE VII
12. BARE BOARDS SHALL BE TESTED USING CAD GENERATED NET LIST
13. OUTER COPPER WEIGHT: 2OZ
14. INNER COPPER WEIGHT 1OZ

ASSY NOTES:

1. ASSEMBLE PER IPC–A–610 CLASS 2
2. ASSEMBLE USING SAC305 SOLDER
3. DO NOT POPULATE THE FOLLOWING COMPONENTS: R68, C80

△4 ADHERE COMPONENTS C54, C51, C55, C50 AND L2 USING DOW CORNING DOWSIL 744 RTV ADHESIVE SEALANT OR EQUIVALENT NEUTRAL CURE SILCONE ADHESIVE
KEEP ADHESIVE OUT OF MARKED AREA (ALSO MARKED ON SILKSCREEN)

DRAGONFLY POWER SYSTEMS
Sheet:
File: POWERCORE–V2.0_MOTHERBOARD.kicad_pcb
Title: PC–02 EDM PULSE GENERATOR
Size: A3 Date: **Rev:**
KiCad E.D.A. kicad 7.0.1 Id: 1/1